ABSTRACT

A quartz glass jig for a processing apparatus using plasma, wherein the surface is subjected to griding working and has a surface roughness Ra in the range of from 2 μ m to 0.05 μ m and microcracks of grinding marks formed during the grinding working have a depth of 50 μ m or less, and the surface roughness Ra od a sand-blasted jig is 2 μ m to 0.05 μ m and depth of a microcrack formed during the sandblast working is 50 μ m or less.



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